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(54) Title: PROCESSING SEMICONDUCTOR WAFERS USING NEAR EDGE REGION ROUNDNESS

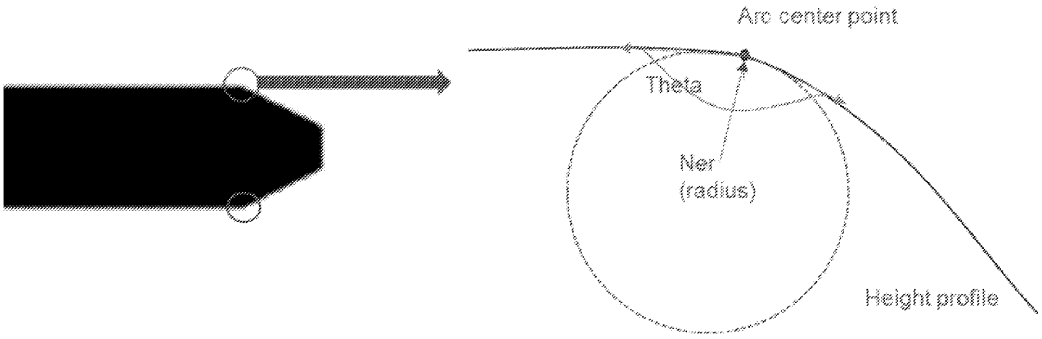


FIG. 4

(57) Abstract: A computer device for analyzing a processed product includes at least one processor in communication with at least one memory device. The at least one processor is programmed to: a) receive scan data of a first inspection of a first product being assembled after the first product has been processed by a tool; b) determine an edge profile for the product based upon the scan data; c) determine a center point for the edge profile; d) generate a best fit circle based upon the edge profile and the center point; e) calculate a NER radius for the first product based upon the best fit circle; and f) adjust operation of the tool based upon the NER radius.

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